

MA4X724 (MA724)

Silicon epitaxial planar type

For super high speed switching

For small current rectification

■ Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Two MA3X721 (MA721) is contained in one package (of a type in the same direction)
- Forward current (Average) $I_{F(AV)} = 200$ mA rectification is possible

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Peak forward current	Single	I_{FM}	300 mA
	Double *1		225
Forward current (Average)	Single	$I_{F(AV)}$	200 mA
	Double *1		150
Non-repetitive peak forward surge current *2	Single	I_{FSM}	1 A
	Double *1		0.75
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Value of each diode in double diodes used.

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

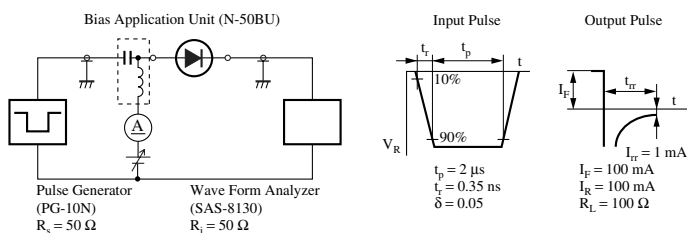
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200$ mA			0.55	V
Reverse current	I_R	$V_R = 30$ V			50	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{tr} = 10$ mA, $R_L = 100$ Ω		3.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

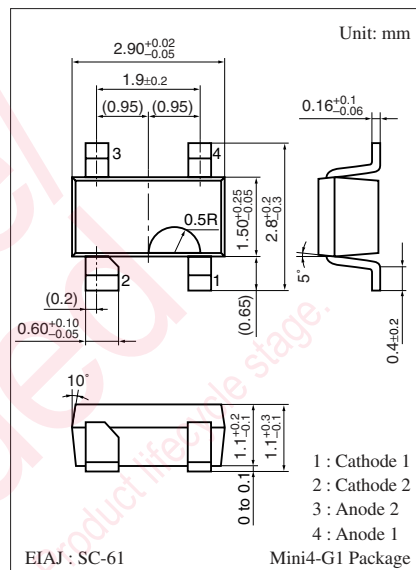
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 1 GHz.

4. *: t_{rr} measurement circuit

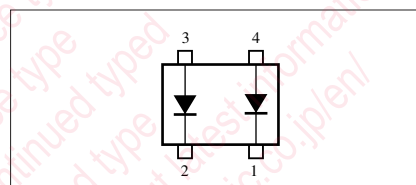


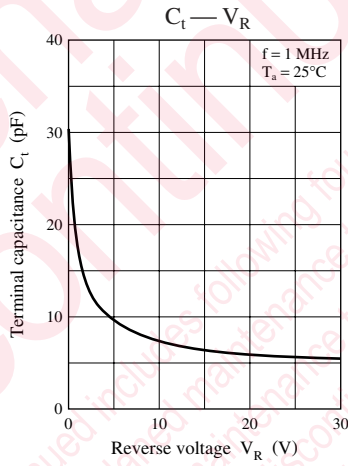
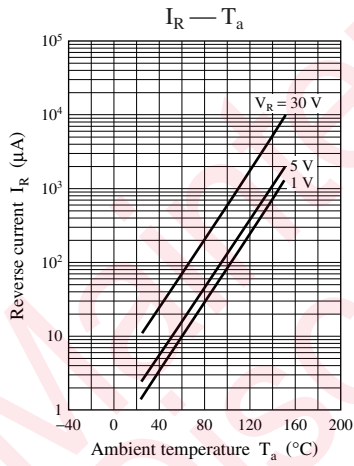
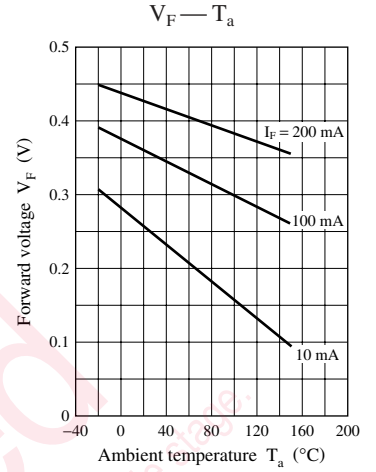
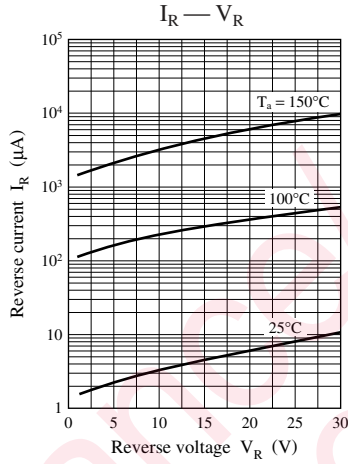
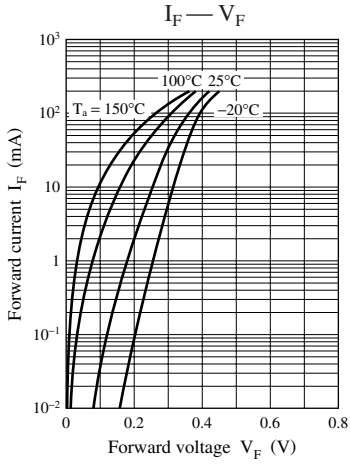
Note) The part number in the parenthesis shows conventional part number.



Marking Symbol: M1T

Internal Connection





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